MICROWAVE POWER GaAs FET

Internally Matched Power GaAs FETs (X, Ku-Band)

Features

- High power
 - P_{1dB} = 39.5 dBm at 9.5 GHz to 10.5 GHz
- High gain
 - $_{-}$ G_{1dB} = 6.0 dB at 9.5 GHz to 10.5 GHz
- Broadband internally matched
- Hermetically sealed package

RF Performance Specifications ($T_a = 25^{\circ}C$)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Output Power at 1dB Compression Point	P _{1dB}	V _{DS} = 9V f = 9.5 - 10.5 GHz	dBm	38.5	39.5	-
Power Gain at 1dB Compression Point	G _{1dB}		dB	5.0	6.0	-
Drain Current	I _{DS}		Α	-	3.4	4.4
Power Added Efficiency	η_{add}		%	-	22	-
Channel-Temperature Rise	ΔT_{ch}	V _{DS} x I _{DS} x R _{th (c-c)}	°C	-	-	80

Electrical Characteristics (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	V _{DS} = 3V I _{DS} = 4.0A	mS	-	2400	-
Pinch-off Voltage	V _{GSoff}	V _{DS} = 3V I _{DS} = 120 mA	V	-2	-3.5	-5
Saturated Drain Current	I _{DSS}	$V_{DS} = 3V$ $V_{GS} = 0V$	Α	-	8.0	10.4
Gate-Source Breakdown Voltage	V _{GSO}	I _{GS} = -120 μA	V	-5	-	-
Thermal Resistance	R _{th (c-c)}	Channel to Case	°C/W	-	1.6	2.5

The information contained herein is presented only as guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA or others. These TOSHIBA products are intended for usage in general electronic equipments (office equipment, communication equipment, measuring equipment, domestic electrification, etc.) Please make sure that you consult with us before you use these TOSHIBA products in equipments which require high quality and/or reliability, and in equipments which could have major impact to the welfare of human life (atomic energy control, spaceship, traffic signal, combustion control, all types of safety devices, etc.). TOSHIBA cannot accept liability to any damage which may occur in case these TOSHIBA products were used in the mentioned equipments without prior consultation with TOSHIBA.

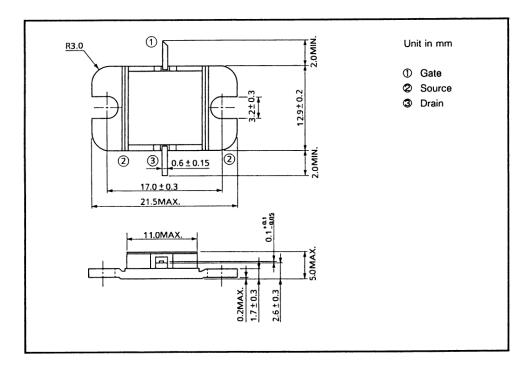
TOSHIBA CORPORATION MW50040196 1/5

The information contained here is subject to change without notice.

Absolute Maximum Ratings ($T_a = 25^{\circ}C$)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V _{DS}	V	15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _D	Α	10.4
Total Power Dissipation (T _c = 25°C)	P _T	W	60
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65 ~ 175

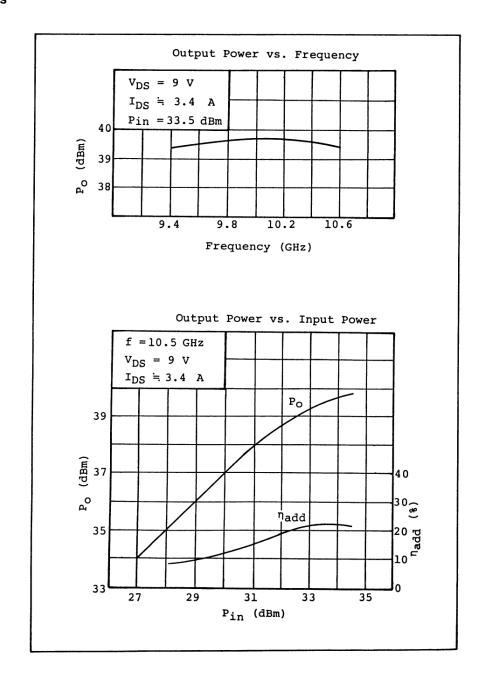
Package Outline (2-11C1B)



Handling Precautions for Packaged Type

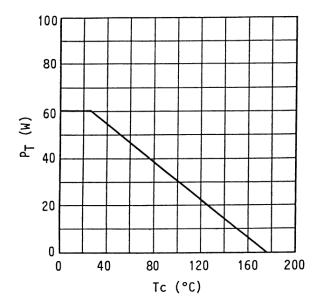
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF Performances



3/5

Power Dissipation vs. Case Temperature



MW50040196

4/5

5/5

TIM0910-8 S-Parameters (Magn. and Angles)

$$V_{DS} = 9 V I_{DS} = 3.4 A$$

